

FLEX-BX200-C246

2U AI Modular PC with 8th/9th Generation LGA 1151 Intel® Core™ i7/i5/i3, Pentium® and Xeon® Processor



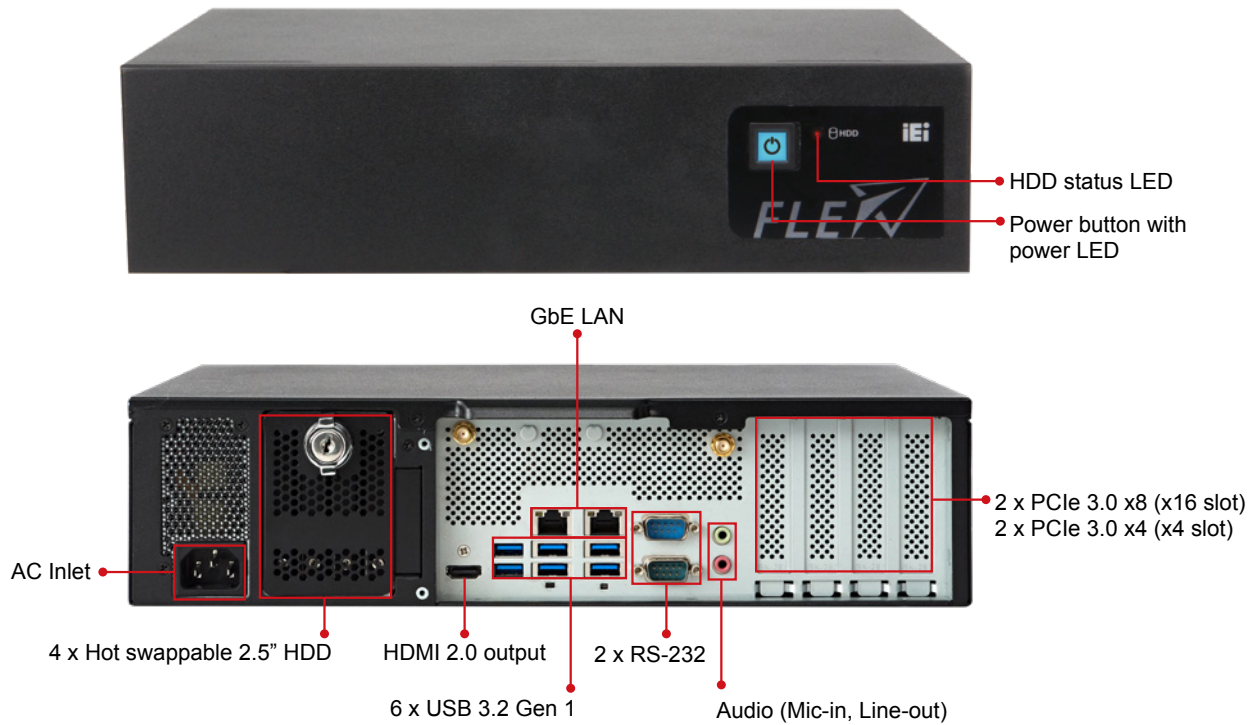
Features

- 2U AI Modular PC supports 8th/9th Gen. LGA 1151 Intel® Core™ i7/i5/i3 and Pentium® processor with Intel® Q370 chipset, or Intel® Xeon® Processor with Intel® C246 chipset
- Four hot-swappable and accessible HDD drive bays, support RAID 0/1/5/10
- Two PCIe 3.0 by 4 and two PCIe 3.0 by 8 slots
- M.2 2280 PCIe Gen 3.0 x4 NVMe™ SSD support

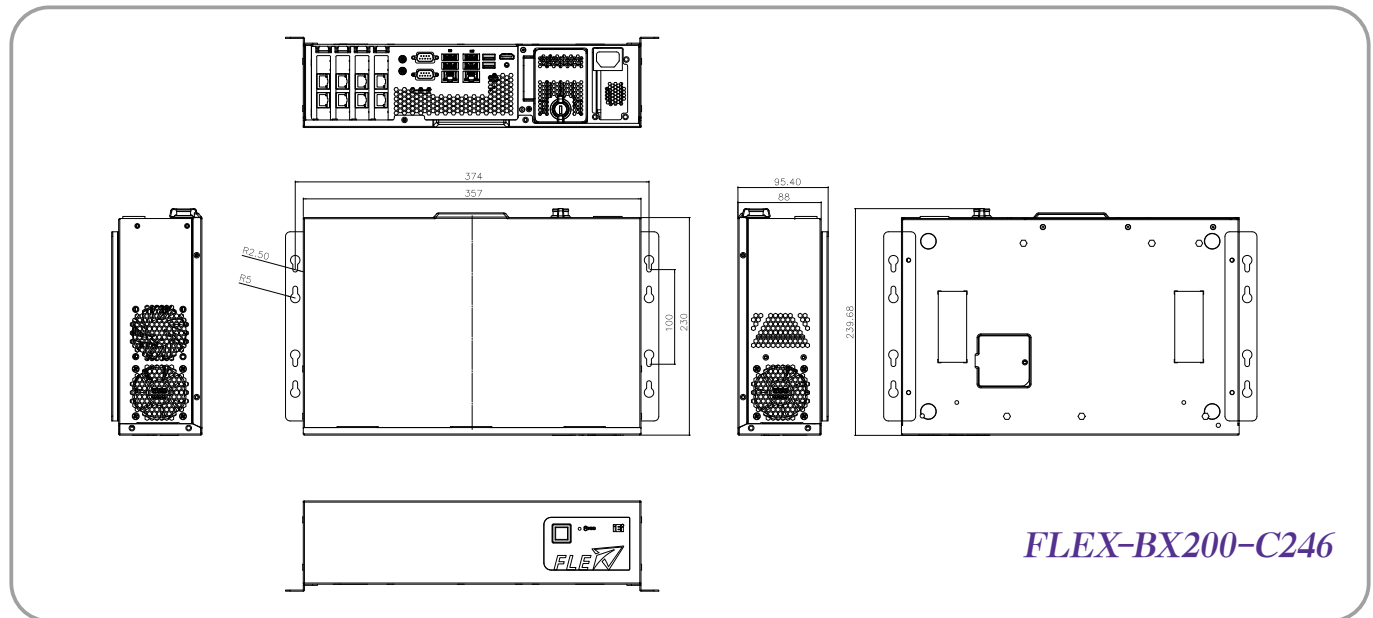
Specifications

Model Name	FLEX-BX200-C246
CPU	Intel® Xeon® E-2176G Processor in the LGA 1151 package
Chipset	Intel® C240 Series Chipsets C246 (Coffee Lake)
Memory	2 x 288-pin 2666/2400 MHz dual-channel DDR4 SDRAM ECC and non-ECC unbuffered DIMMs support up to 64 GB
Graphics Engine	Intel® HD Graphics Gen 9 Engines with Low power 16 execution unit, supports DX2015, OpenGL 5.X and OpenCL2.x, ES 2.0
Ethernet	Intel® I211/I219 controller
Storage	4 x accessible 2.5" HDD/SSD SATA 6 Gb/s bay (with RAID 0/1/5/10 support) with LED indicator 1 x NGFF M.2(2280) M Key socket (support NVMe SSD)
I/O Ports and Switches	1 x HDMI output 2 x GbE LAN 6 x USB 3.2 Gen 1 (5Gb/s) Type-A 2 x RS-232 DB-9 type 1 x Mic in 1 x Line out 1 x AC Inlet Power button with power LED (power on=Blue) AT/ATX mode switch Reset button
Expansion Slots	2 x PCIe 3.0 by 8 (by 16 slot) 2 x PCIe 3.0 by 4 (Maximum card size supported: 68 mm x 167 mm) 1 x NGFF M.2 (2230) A Key socket (support Wi-Fi) 1 x NGFF M.2 (3042) B Key socket (support WWAN wits SIM slot)
Thermal Solution	System Fan x3, CPU Cooler x1
Power supply	AC input ATX power supply 350W power supply - Input: 115VAC~264VAC, 50/60Hz - Output (Max.): 3.3V@14A, 5V@16A, 12V@29A, -12V@0.3A, +5Vsb@3A - Efficiency: Full load (100%) 87%, Typical load (50%) 90%, Light load (20%) 87%
Watchdog Timer	Software Programmable support 1 ~ 255 sec. System reset
Chassis Construction	Metal Housing
Mounting	Wall and Rack Mount
Color	Black
Dimensions (LxDxH) (mm)	357 x 230 x 88
Weight (kg) Net/Gross	4/6
Operating Temperature	-20°C ~ 40°C (with SSD and TDP 80W processor)
Storage Temperature	-20°C ~ 60°C
Operating Humidity	5% ~ 95%, non-condensing
Vibration	5 ~ 17Hz, 0.1 double amplitude displacement 17 ~ 640Hz 1.5G acceleration peak to peak
shock	10G acceleration part to part (11ms)
Supported OS	Microsoft Windows 10 / Windows 11, Linux

Fully Integrated I/O



Dimensions (Unit: mm)



Ordering Information

Part No.	Description
FLEX-BX200-C246-XE/35-R20	2U AI Modular Box PC, Intel® Xeon® E-2176G Processor (6-core, 12-thread, 3.7 GHz), TDP 80W, two PCIe x4 and two PCIe x8 slots, four HDD bays, 350W PSU, R20
FLEX-BX200-Q370-P/35-R20	2U AI Modular Box PC, Intel® Pentium® Gold G5400T Processor (2-core, 4-thread, 3.10 GHz) TDP 35W, two PCIe x4 and two PCIe x8 slots, four HDD bays, 350W PSU, R20
FLEX-BX200-Q370-I3/35-R20	2U AI Modular Box PC, Intel® Core™ i3-8100T Processor (4-core, 4-thread, 3.10 GHz) TDP 35W, two PCIe x4 and two PCIe x8 slots, four HDD bays, 350W PSU, R20
FLEX-BX200-Q370-I5/35-R20*	2U AI Modular Box PC, Intel® Core™ i5-8500T Processor (6-core, 6-thread, 2.1 GHz) TDP 35W, two PCIe x4 and two PCIe x8 slots, four HDD bays, 350W PSU, R20
FLEX-BX200-Q370-I7/35-R20*	2U AI Modular Box PC, Intel® Core™ i7-8700T Processor (6-core, 12-thread, 2.4 GHz) TDP 35W, two PCIe x4 and two PCIe x8 slots, four HDD bays, 350W PSU, R20

Options

Part No.	Description
FLEX-BXRK-R10	Rack mount kit

Packing List

Item	Qty	Remark
32702-000200-100-RS	1	European power cord, 1830mm
41020-0521C2-00-RS	2	wall mount kit, black
44035-040062-RS	4	M4 x 6 oval head screw for wall mount kit, black
	1	Key for HDD cover